Product Information

Zytel® HTN

high performance polyamide resin

Zytel® HTNFR52G30LX NC010

30% Glass Reinforced, Flame Retardant, High Performance Polyamide Resin
for Pb free soldering system

Property	Test Method	Units	FR52G30LX NC010
			Measured at 23℃ D.A.M.
Mechanical			
Stress at Break	ISO 527	MPa	181
Strain at Break	ISO 527	%	2.5
Tensile Modules	ISO 527	MPa	10,000
Notched Charpy Impact	ISO 179	KJ/m^2	13
Thermal			
HDT(.045MPa)			
HDT(1.82MPa)	ISO 75-1&2	℃	282
Melting Temperature	ISO 3146C	℃	311
Density	ISO 1183	Kg/m^3	1630
Electrical			
Relative Permitivity	IEC 60250	MHz	3.84
Dissipation Factor	IEC 60250		0.015
Ark Resistance	UL746A	V	113
Dielectric Strength	IEC 60243-1	KV/mm	24.2
Volume Resistivity	IEC 60093	ohm	1.48x10^15
Surface Resistivity	IEC 60093	ohm	3.67x10^15
Processing			
Resin Temp		℃	325-330
Molding Temp		℃	60-130
Dry Condition			100C x 6Hrs
Processing Moisture Content		%	<0.1

Contact DuPont for Material Safety Data Sheet, general guides and/or additional information about ventilation, handling, purging, drying, etc.
ISO Mechanical properties measured at 4.0mm, ISO Electrical properties measured at 2.0mm, and all ASTM properti

The above data are preliminary and are subject to change as additional data are developed on subsequent lots.

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